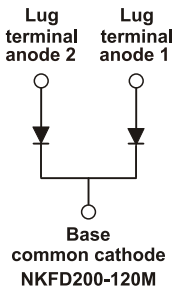
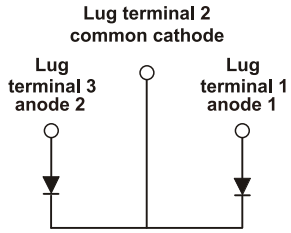
FRED
Ultrafast Soft Recovery Diode Module
100A x 2 / 1200V

TO-244M (non-insulated)

TO-244M (insulated)

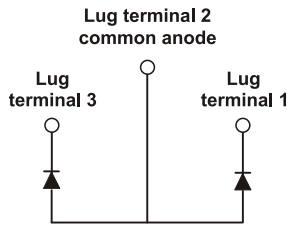


NKFD200-120M



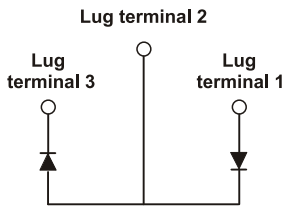
NKFD200-120IM

*Add suffix "I" for insulated type



NKFD200-120RIM

*Add suffix "R" for common anode



NKFD200-120AIM

*Add suffix "A" for half-bridge

FEATURES

- Very low Q_{rr} and t_{rr}
- Lead (Pb)-free
- Designed and qualified for industrial level
- Reduced RFI and EMI
- Reduced snubbing
- Planar FRED Chip
- Epoxy molding structure (TO-244M)

TYPICAL APPLICATIONS

- Power converters
- Motor drives
- Welders
- Switching power supplies
- Battery chargers
- DC choppers
- Inverters

DESCRIPTION

FRED diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems .
An extensive characterization of the recovery behavior for different values of current, temperature and dI/dt simplifies the calculations of losses in the operating conditions.The softness of the recovery eliminates the need for a snubber in most applications.

PRODUCT SUMMARY	
$I_{F(AV)}$	200A
V_R	1200V
$I_{F(AV)}$ at T_C per diode	100A at 110 °C

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS		MAX.	UNIT
Cathode to anode voltage	V_R			1200	V
Average forward current	$I_{F(AV)}$	T_C =110°C	per module	200	A
			per leg	100	
Single pulse forward current	I_{FSM}	Limited by junction temperature, per leg		1000	
Maximum power dissipation	P_D	T_C =25°C		440	W
		T_C =100°C		260	
Operating junction and storage temperature range	T_J, T_{Stg}			- 55 to 175	°C

ELECTRICAL SPECIFICATIONS (T_J = 25 ºC unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Cathode to anode breakdown voltage	V_{BR}	I_R = 100 µA	1200	-	-	V
Maximum forward voltage	V_{FM}	I_F = 100 A	-	2.00	2.20	
		I_F = 200 A	-	2.30	-	
		I_F = 100 A, T_J = 125 ºC	-	1.80	-	
Maximum reverse leakage current per leg	I_{RM}	T_J = 125°C, V_R = 1200V	-	-	1.0	mA
		T_J = 25°C, V_R = 1200V	-	0.5	10	µA
Junction capacitance	C_T	V_R = 200V	-	120	-	pF
Series inductance	L_S	From top of terminal hole to mounting plane	-	6.0	-	nH
Maximum RMS insulation voltage (for insulated type)	V_{INS}	50Hz	-	-	2500(1min)	V
					3000(1s)	

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T_J= 25 ºC unless otherwise specified)

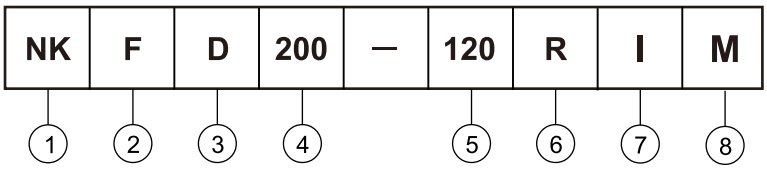
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Reverse recovery time	t_{rr}	I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A		-	110	140	ns
		I_F = 1.0A, dI_F/dt=200A/µs, V_R = 30V		-	70	-	
		T_J = 25 ºC	I_F= 160A dI_F/dt = 200 A/µs V_R = 200 V	-	150	200	
		T_J= 125 ºC		-	-	320	
Peak recovery current	I_{RRM}	T_J= 25 ºC		-	20	22	A
		T_J= 125 ºC		-	-	40	
Reverse recovery charge	Q_{rr}	T_J= 25 ºC		-	2000	2400	nC
		T_J= 125 ºC		-	-	6200	
Peak rate of recovery current	$dI_{(rec)M}/dt$	T_J = 25 ºC		-	-	300	A/µs
		T_J= 125 ºC		-	-	210	

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER		**SYMBOL**	**MIN.**	TYP.	**MAX.**	**UNIT**
Maximum junction and storage temperature range		T_J, T_{stg}	-55	-	175	ºC
Thermal resistance, junction to case per leg	TO-244M (non-insulated)	R_{thJC}	-	-	0.12	ºC/W
	TO-244M (insulated)		-	-	0.20	
Thermal resistance, junction to case per module	TO-244M (non-insulated)	R_{thJC}	-	-	0.060	
	TO-244M (insulated)		-	-	0.10	
Typical thermal resistance, case to heatsink		R_{thCS}	-	0.10	-	
Weight	TO-244M (non-insulated)		-	80 (2.82)	-	g (oz.)
	TO-244M (insulated)		-	95 (3.36)	-	
Mounting torque(1)			30 (3.4)	-	40 (4.6)	lbf·in (N·m)
Mounting torque center hole			12 (1.4)	-	18 (2.1)	
Terminal torque			30 (3.4)	-	40 (4.6)	
Vertical pull			-	-	80	lbf·in
2″ lever pull			-	-	35	

Note
(1)Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf. in steps until desired or maximum torque limits are reached

Ordering Information Table

Device code



1 - Nell's power module
2 - F for Ultrafast soft recovery diode
3 - D for Dual Diodes, TO-244 Package
4 - Maximum average forward current, 200 = 100A x 2
5 - Voltage rating (120 = 1200V)
6 - None for common cathode configuration
"R" for common anode configuration,
"A" for half bridge configuration
7 - None for non-insulated type
"I" for insulated type
8 - M for Molding structure

Fig.1 Typical forward voltage drop vs. Instantaneous forward current (per leg)

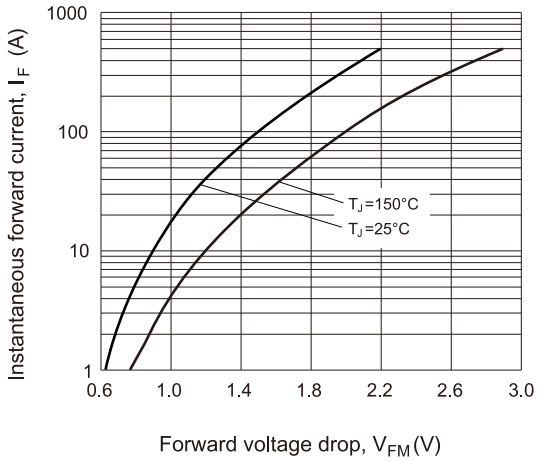


Fig.2 Typical reverse current vs. reverse voltage (per leg)

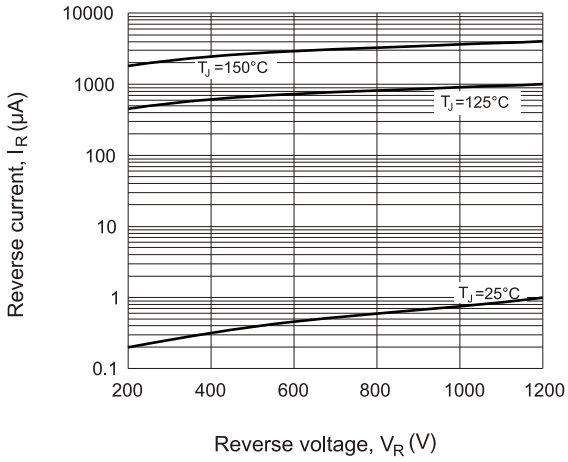


Fig.3 Typical junction capacitance vs. reverse voltage (per leg)

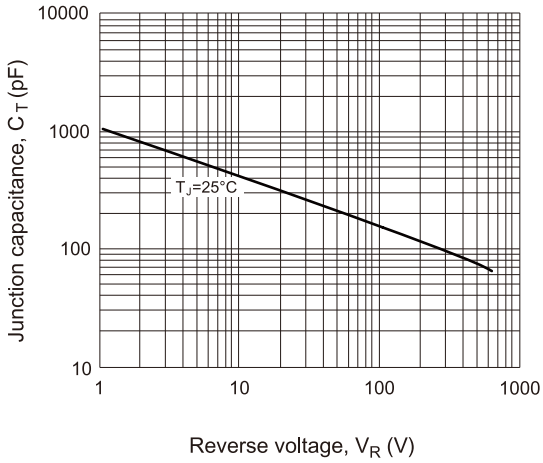


Fig.4 Maximum allowable case temperature vs. average forward current (per leg)

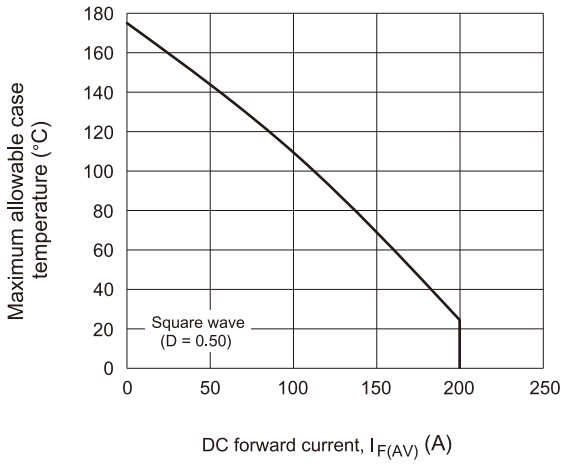


Fig.5 Typical reverse recovery time vs. dI_F/dt (per leg)

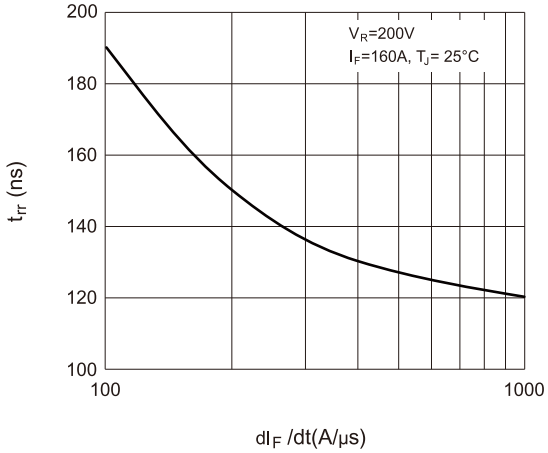


Fig.6 Typical recovery current vs. dI_F/dt (per leg)

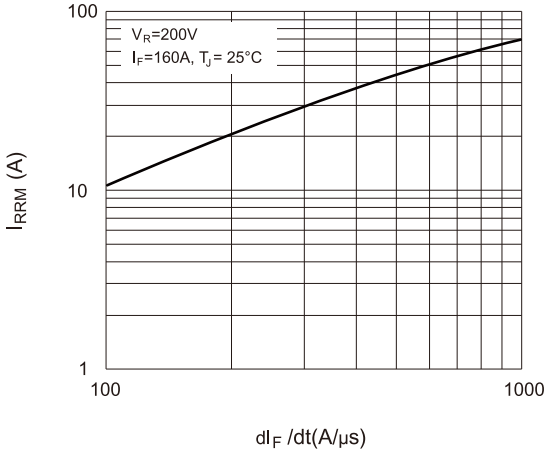


Fig.7 Typical stored charge vs. dI_F/dt (per leg)

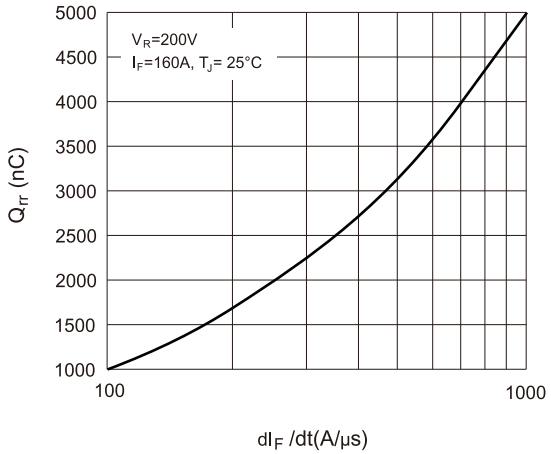


Fig.8-1 Maximum thermal impedance $R_{th(j-c)}$ characteristics (per leg, for TO-244M non-insulated)

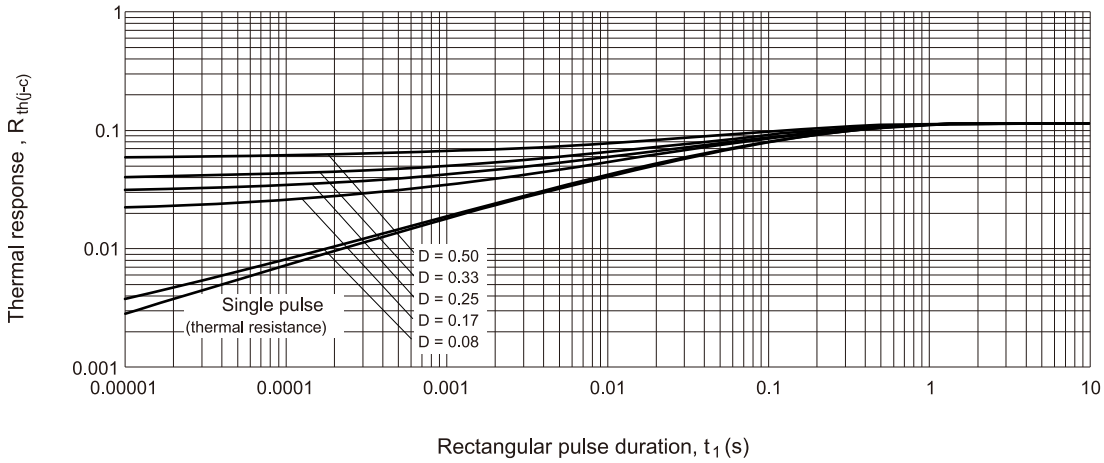


Fig.8-2 Maximum thermal impedance $R_{th(j-c)}$ characteristics (per leg, for TO-244M insulated)

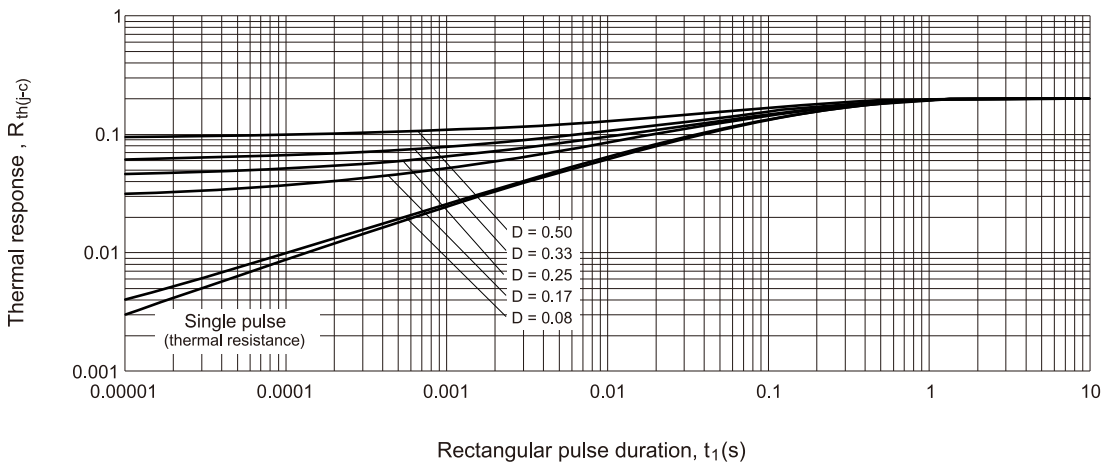


Fig.9 Reverse recovery parameter test circuit

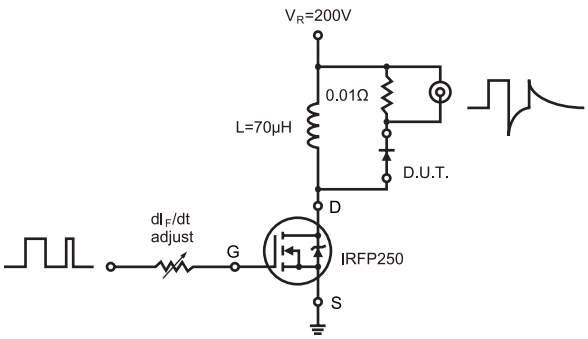
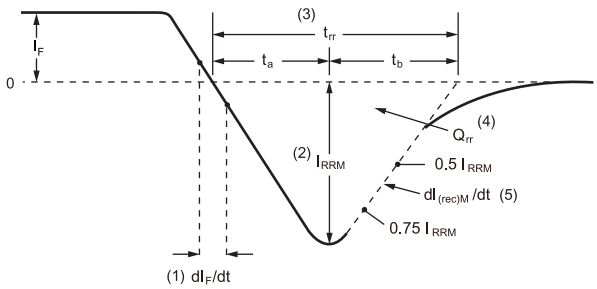


Fig.10 Reverse recovery waveform and definitions



(1) dI_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

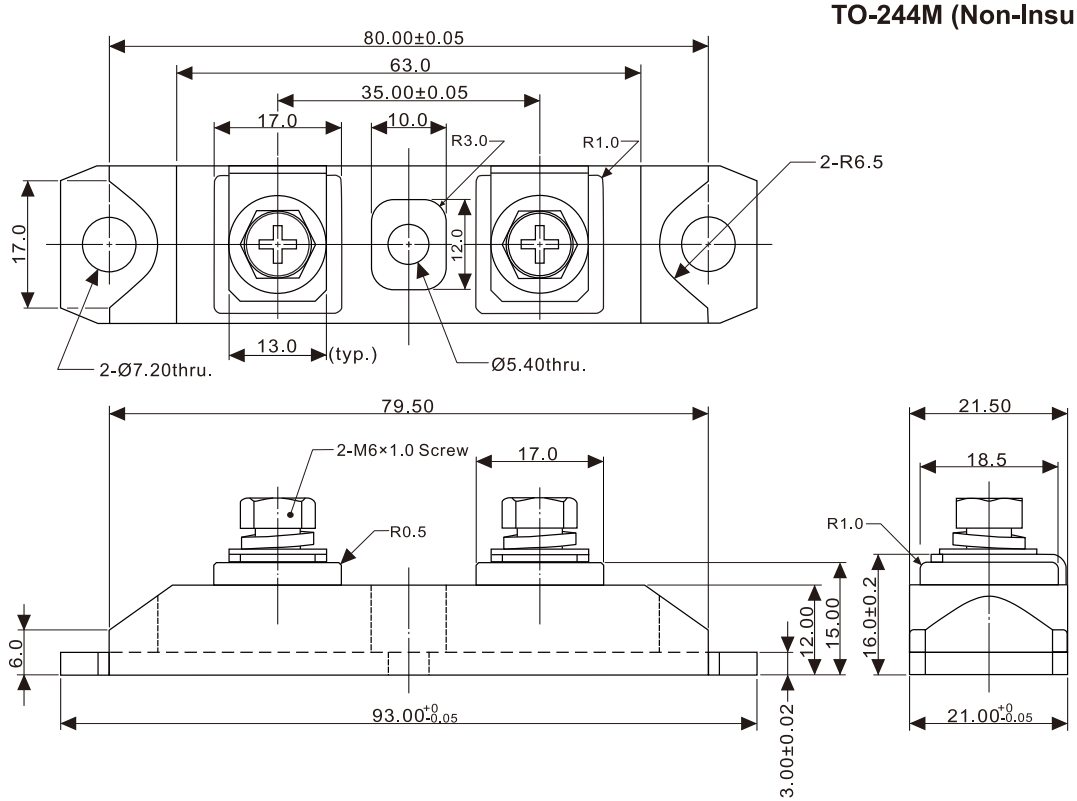
(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

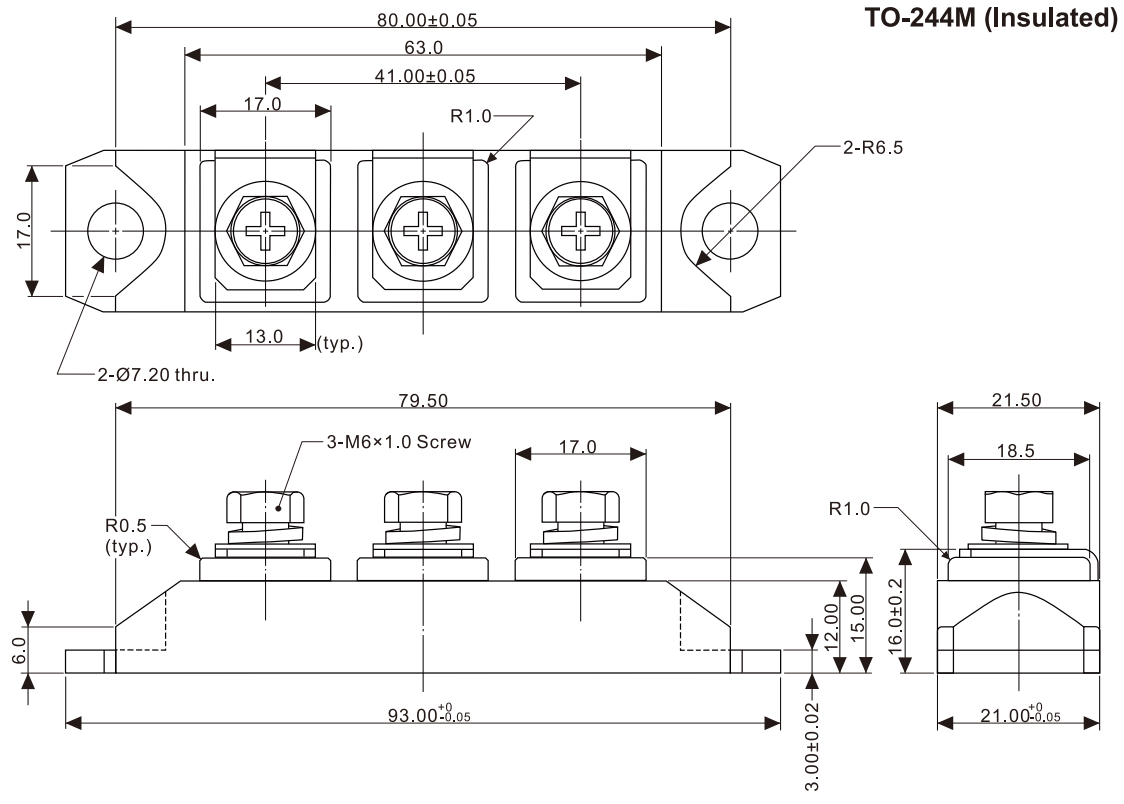
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

TO-244M (Non-Insulated)



All dimensions in millimeters

TO-244M (Insulated)



All dimensions in millimeters